Product / Package Information

Package	SOT23
Body Size	
Lead Count	5
Terminal Finish	100 Sn
MS Number	MS010611C

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	7.01 E-03	87.30	873000	41.80	417950
Thermosets	Phenol Resin	Proprietary	3.61 E-04	4.50	45000	2.15	21544
Thermosets	Epoxy Resin 1	Proprietary	2.41 E-04	3.00	30000	1.44	14363
Thermosets	Epoxy Resin 2	Proprietary	2.41 E-04	3.00	30000	1.44	14363
Others	Others	Proprietary	1.61 E-04	2.00	20000	0.96	9575
Other inorganic materials	Carbon Black	1333-86-4	1.61 E-05	0.20	2000	0.10	958
Subtotal			8.03 E-03	100.0	1000000	47.88	478752

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	6.95 E-03	97.5	975000	41.43	414350
Copper & its alloys	Iron	7439-89-6	1.68 E-04	2.35	23500	1.00	9987
Copper & its alloys	Zinc	7440-66-6	8.55 E-06	0.12	1200	0.05	510
Copper & its alloys	Phosphorus	7723-14-0	2.14 E-06	0.03	300	0.01	127
Subtotal			7.13 E-03	100	1000000	42.50	424974

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	7.20 E-05	100	1000000	0.43	4293

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	3.23 E-04	100	1000000	1.92	19246

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.50 E-04	99.99	1000000	0.89	8942

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.00 E-03	100	1000000	5.96	59620

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.64 E-05	80.50	805000	0.34	3360
Other organic materials	Carbocyclic Acrylates	Proprietary	7.00 E-06	10.00	100000	0.04	417
Other organic materials	Bismaleimide resin	Proprietary	2.10 E-06	3.00	30000	0.01	125
Other organic materials	2-preponoic acid, 2-methyl	68586-19-6	2.10 E-06	3.00	30000	0.01	125
Others	Additive	Proprietary	2.10 E-06	3.00	30000	0.01	125
Other organic materials	Dicumyl peroxide	80-43-3	3.50 E-07	0.50	5000	0.002	21
Subtotal			7.00 E-05	100.00	1000000	0.42	4173

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.68 E-02**	**100**	**1000000**

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ANALOG DEVICES
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Product / Package Information

Package	SOT23
Body Size	
Lead Count	5
Terminal Finish	SnPb
MS Number	MS011616A

Environmental Information

RoHS Compliant	No
High Temperature Compliant	No
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	7.01 E-03	87.3	873000	41.79	417949
Thermosets	Phenol Resin	Proprietary	3.61 E-04	4.5	45000	2.15	21544
Thermosets	Epoxy Resin 1	Proprietary	2.41 E-04	3.0	30000	1.44	14363
Thermosets	Epoxy Resin 2	Proprietary	2.41 E-04	3.0	30000	1.44	14363
Others	Others	Proprietary	1.61 E-04	2.0	20000	0.96	9575
Other inorganic materials	Carbon Black	1333-86-4	1.61 E-05	0.2	2000	0.10	958
Subtotal			8.03 E-03	100.0	1000000	48	478750

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	6.95 E-03	97.5	975000	41.43	414348
Copper & its alloys	Iron	7439-89-6	1.68 E-04	2.35	23500	1.00	9987
Copper & its alloys	Zinc	7440-66-6	8.55 E-06	0.12	1200	0.05	510
Copper & its alloys	Phosphorus	7723-14-0	2.14 E-06	0.03	300	0.01	127
Subtotal			7.13 E-03	100	1000000	42	424973

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	7.20 E-05	100	1000000	0.43	4293

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.74 E-04	85	850000	1.64	16361
Tin & its alloys	Lead	7439-92-1	4.84 E-05	15	150000	0.29	2887
Subtotal			3.23 E-04	100	1000000	1.92	19248

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.50 E-04	99.99	1000000	0.89	8943

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.00 E-03	100	1000000	5.96	59620

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.60 E-05	80.00	800000	0.33	3339
Other organic materials	Epoxy Resin	Proprietary	1.05 E-05	15.00	150000	0.06	626
Others	Curing agent & hardener	Proprietary	3.50 E-06	5.00	50000	0.02	209
Subtotal			7.00 E-05	100	1000000	0.42	4173

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.68 E-02**	**100**	**1000000**

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ANALOG DEVICES

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Product / Package Information	
Package	SOT23 - COL
Body Size	
Lead Count	5
Terminal Finish	NiPdAu
MS Number	MS011613A

Environmental Information	
RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	6.68 E-03	83.25	832500	40.59	405911
Thermosets	Epoxy resin	158117-90-9 / 85954-11-6	4.35 E-04	5.42	54200	2.64	26427
Thermosets	Phenol resin	26834-02-6	2.77 E-04	3.45	34500	1.68	16822
Other inorganic materials	Metal Hydroxide	1309-42-8 / 20427-58-1	4.35 E-04	5.42	54200	2.64	26427
Others	Others	Proprietary	1.98 E-04	2.46	24600	1.20	11994
Subtotal			8.03 E-03	100.0	1000000	48.76	487580

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	6.95 E-03	97.5	975000	42.20	421991
Copper & its alloys	Iron	7439-89-6	1.68 E-04	2.35	23500	1.02	10171
Copper & its alloys	Zinc	7440-66-6	8.55 E-06	0.12	1200	0.05	519
Copper & its alloys	Phosphorus	7723-14-0	2.14 E-06	0.03	300	0.01	130
Subtotal			7.13 E-03	100	1000000	43.28	432811

Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	8.28 E-05	90.91	909091	0.50	5028
Precious metals	Palladium	7440-05-3	7.20 E-06	7.91	79051	0.04	437
Precious metals	Gold	7440-57-5	1.08 E-06	1.19	11858	0.01	66
Subtotal			9.11 E-05	100.00	1000000	0.55	5530

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.50 E-04	99.99	1000000	0.91	9108

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.00 E-03	100	1000000	6.07	60720

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Aluminum oxide	1344-28-1	2.45 E-05	35.00	350000	0.15	1488
Other organic materials	Diethylene glycol monoethyl ether acetate	112-15-2	2.45 E-05	35.00	350000	0.15	1488
Thermoset	Epoxy Resin	Proprietary	1.75 E-05	25.00	250000	0.11	1063
Others	Amine	Proprietary	3.50 E-06	5.00	50000	0.02	213
Subtotal			7.00 E-05	100.00	1000000	0.43	4250

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.65 E-02**	**100**	**1000000**

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